Electronic Acknowledgement Receipt FES ID: 1100889 Application Number: 10810965 Confirmation Number: 9818 Title of Invention: Novel method to improve bump reliability for flip chip device First Named Inventor: Yen-Ming Chen Customer Number: 47390 Filer: Daniel R. McClure Filer Authorized By: Attorney Docket Number: TS01-0413C Receipt Date: 01-JUL-2006 Filing Date: 26-MAR-2004 Time Stamp: 09:42:52 Application Type: Utility International Application Number: Payment information:

File Listing:

Submitted with Payment

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Amendment After Final	00394666.pdf	142800	no	9

no

warnings:			
Information:			
	Total Files Size (in bytes):	142800	

This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.

New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/IDO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filling Receipt, in due course.